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Bib Data Sheet

CONFIRMATION NO. 5651

SERIAL NUMBER 10/767,623	FILING DATE 01/28/2004 RULE	CLASS 257	GROUP ART UNIT 2823	ATTORNEY DOCKET NO. JCLA8288-D
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APPLICANTS

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** CONTINUING DATA *****

This application is a DIV of 10/144,121 05/10/2002

yes K.N.

VIA Technology, INC.

** FOREIGN APPLICATIONS *****

TAIWAN 90132738 12/28/2001

yes K.N.

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 06/16/2004

Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	COUNTRY	DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged <i>K.N.</i> Examiner's Signature Initials	TAIWAN	5	8	1

ADDRESS

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TITLE

Semiconductor packaging substrate and method of producing the same

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